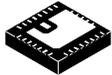


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

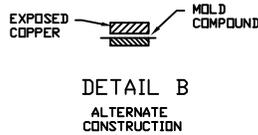
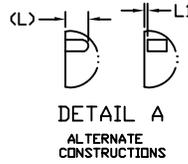
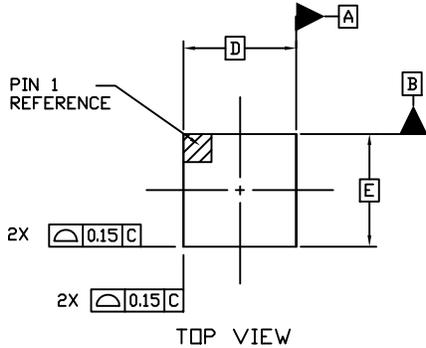
ON Semiconductor®



SCALE 2:1

QFN28 4x4, 0.4P
CASE 485EA
ISSUE A

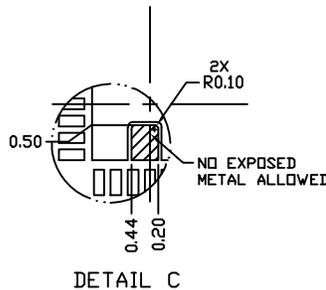
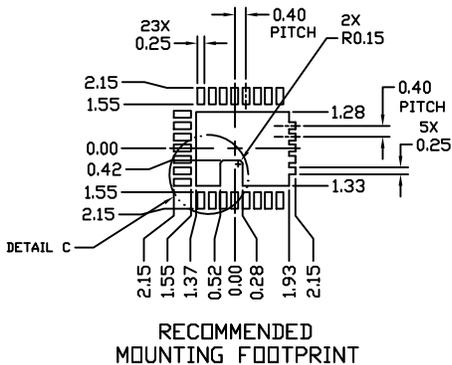
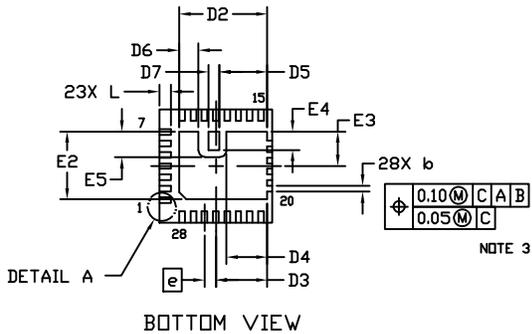
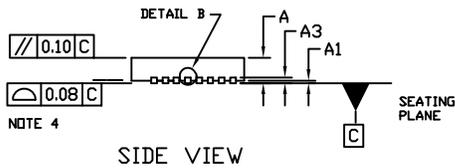
DATE 17 DEC 2015



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN.	MAX.
A	0.90	1.10
A1	0.00	0.05
A3	0.20 REF	
<i>b</i>	0.15	0.25
D	4.00 BSC	
D2	3.07	3.17
D3	1.77	1.87
D4	1.39	1.49
D5	1.64	1.74
D6	0.63	0.73
D7	0.35	0.45
E	4.00 BSC	
E2	2.36	2.46
E3	1.18	1.28
E4	0.61	0.71
E5	0.86	0.96
<i>e</i>	0.40 BSC	
L	0.30	0.50
L1	---	0.15



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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QFN28 4X4, 0.4P	PAGE 1 OF 2

